

# SSC8LA2GN6

## **N-Channel Enhanced MOSFET**

#### > Features

VDS	VGS	RDSON Typ.	ID
100V	1201/	6mR@10V	82A
	±20V	8.5mR@4V5	

#### > Description

This device is N-Channel enhancement MOSFET. Uses SGT technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. 100% UIS + DVDS Tested.

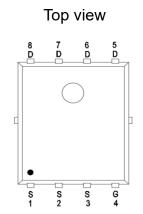
## Applications

- DC/DC converters
- Power supplies
- Motor Drive Control
- Synchronous rectification

## > Ordering Information

Device	Package	Shipping
SSC8LA2GN6	PDFN5X6	5000/Reel

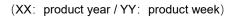
## Pin configuration







#### Marking



## > Absolute Maximum Ratings(T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit		
VDSS	Drain-to-Source Voltage		100	V	
V <sub>GSS</sub>	Gate-to-Source Volt	Gate-to-Source Voltage		V	
		Tc=25℃	82	٥	
lD	Continuous Drain Current d	Tc=100℃	63	A	
-		T <sub>A</sub> =25℃	28	•	
IDSM	Continuous Drain Current <sup>a</sup>	T <sub>A</sub> =70°C	18	A	
I <sub>DM</sub>	Pulsed Drain Current <sup>b</sup>		246	А	
	Power Dissipation ° $\frac{T_{C}=25^{\circ}C}{T_{C}=100^{\circ}C}$ $T_{A}=25^{\circ}C$	Tc=25℃	100		
PD		40	W		
		T <sub>A</sub> =25℃	5		
Pdsm	Power Dissipation <sup>a</sup>	T <sub>A</sub> =70°C	3.2	W	
las	Avalanche Current <sup>b</sup> L=0.5mH Single Pulse		11	А	
Eas	Avalanche Energy <sup>b</sup> L=0.5mH Single Pulse		30	mJ	
TJ	Operation junction temperature		-55~150	<u>.</u>	
Tstg	Storage temperature	range	-55~150	°C	

#### > Thermal Resistance Ratings( $T_A=25^{\circ}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
R <sub>θJA</sub>	Junction-to-Ambient Thermal Resistance <sup>a</sup>	25	°C/W
R <sub>θJC</sub>	Junction-to-Case Thermal Resistance	1.25	C/ VV

Note:

- a. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with T<sub>A</sub>=25°C.The value in any given application depends on the user is specific board design. The power dissipation is based on the t ≤ 10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

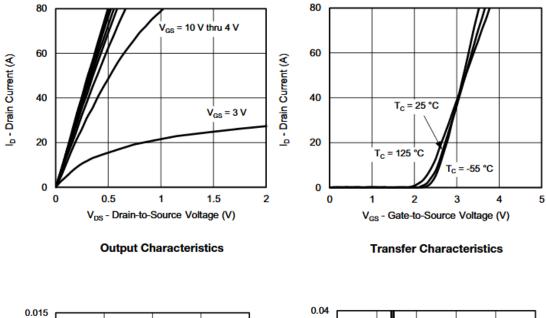


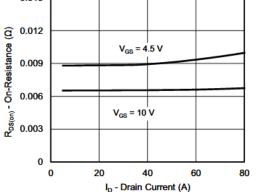
# $\succ$ Electronics Characteristics(T<sub>A</sub>=25 °C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Unit	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	VGS=0V ,ID=250uA	100			V	
$V_{GS \ (th)}$	Gate Threshold Voltage	VDS=VGS ,ID=250uA	1.2	1.7	2.3	V	
	Drain-Source On-	VGS=10V , ID=30A		6	8.5	- mR	
$R_{DS(on)}$	Resistance	VGS=4.5V , ID=20A		8.5	12.5		
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	VDS=80V ,VGS=0V			1	uA	
I <sub>GSS</sub>	Gate-Source leak current	VGS=±20V ,VDS=0V			±100	nA	
G <sub>FS</sub>	Transconductance	VDS=5V ,ID=20A		40		S	
$V_{\text{SD}}$	Forward Voltage	VGS=0V , IS=20A		0.84	1.3	V	
Rg	Gate Resistance	VDS=0V, f=1MHz		2		R	
Ciss	Input Capacitance			2561			
Coss	Output Capacitance	VDS=50V , VGS=0V,		820		pF	
Crss	Reverse Transfer Capacitance	f=1MHz		59		, Pi	
T <sub>D(ON)</sub>	Turn-on delay time			10			
Tr	Rise time	VGS=10V, RL=2.5R		22			
Td(OFF)	Turn-off delay time	VDS=50V , RG=3R		40		ns	
Tf	Fall time			29			
$Q_{G}$	Total Gate Charge			56			
Q <sub>GS</sub>	Gate Source Charge	VGS=10V, VDS=50V		10		nC	
Qgd	Gate Drain Charge	- ID=20A		14			
Trr	Diode Recovery Time	IF=20A , di/dt=200A/us		50		ns	
Qrr	Diode Recovery Charge	IF=20A , di/dt=200A/us		123		nC	

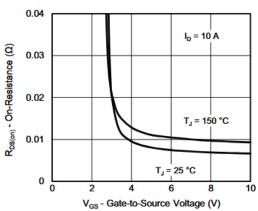


## > Typical Characteristics(T<sub>A</sub>=25°C unless otherwise noted)

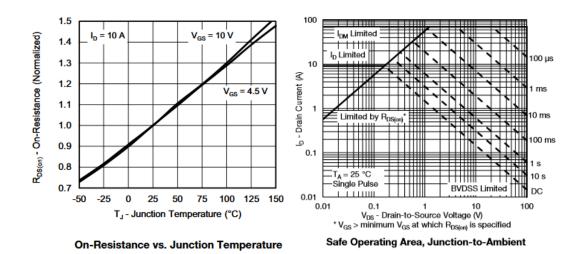




**On-Resistance vs. Drain Current and Gate Voltage** 

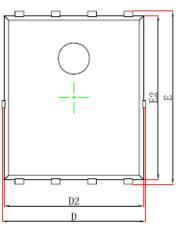


**On-Resistance vs. Gate-to-Source Voltage** 

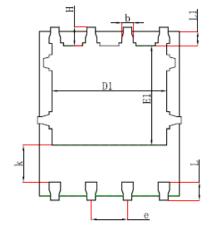




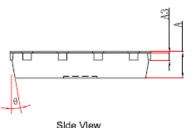
## Package Information







<u>Bottom Vlew</u> [背视图]



<u>Slde Vlew</u> [側视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	0.900	1.000	0.035	0.039	
A3	0.254	1REF	0.010	DREF	
D	4.944	5.096	0.195	0.201	
E	5.974	6.126	0.235	0.241	
D1	3.910	4.110	0.154	0.162	
E1	3.375	3.575	0.133	0.141	
D2	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
k	1.190	1.390	0.047	0.055	
b	0.350	0.450	0.014	0.018	
e	1.270	0.0 OTYP		50TYP	
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	10°	12°	10°	12°	



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